



SDI Review Form 1.6

Journal Name:	Journal of Engineering Research and Reports
Manuscript Number:	Ms_JERR_51870
Title of the Manuscript:	Wire bond Solution of Semiconductor IC Package through Modelling and Simulation
Type of the Article	Original Research Article

General guideline for Peer Review process:

This journal's peer review policy states that **NO** manuscript should be rejected only on the basis of '**lack of Novelty**', provided the manuscript is scientifically robust and technically sound. To know the complete guideline for Peer Review process, reviewers are requested to visit this link:

(<http://www.sciencedomain.org/page.php?id=sdi-general-editorial-policy#Peer-Review-Guideline>)

PART 1: Review Comments

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Compulsory REVISION comments	<p>-----</p> <p>The authors investigated via modeling and simulation done for semiconductor integrated circuit (IC) lead frame package (hereinafter referred to as Device Z) with different wire bond configurations. Results show that copper wire technology offers significant cost savings and could pave the way for more businesses in the plant.</p>	<p>-----</p>
Minor REVISION comments	<p>-----</p>	<p>-----</p>
Optional/General comments	<p>-----</p> <p>---</p>	<p>-----</p>

PART 2:

	Reviewer's comment	Author's comment (if agreed with reviewer, correct the manuscript and highlight that part in the manuscript. It is mandatory that authors should write his/her feedback here)
Are there ethical issues in this manuscript?	(If yes, Kindly please write down the ethical issues here in details)	

Reviewer Details:

Name:	Adel H. Phillips
Department, University & Country	Ain-Shams University, Egypt